

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kai-Chun Hsu	08/17/2010
Yeur-Luen Tu	08/17/2010
Chung Chien Wang	08/26/2010
Tzu-Hsuan Hsu	08/19/2010
Ching-Chun Wang	08/23/2010
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD
Street Address:	No. 8, Li-Hsin Rd., 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12765496
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ATTORNEY DOCKET NUMBER:	24061.1437 / 2009-0789
NAME OF SUBMITTER:	Steven P. Chen

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Total Attachments: 3

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Assignment

Docket No.: 2009-0789 / 24061.1437
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Kai-Chun Hsu of 3F, No. 116, Yongli Rd.
Yonghe City, Taipei County 234, Taiwan, R.O.C.
- (2) Yeur-Luen Tu of No. 3-6, Lane 12, Gong-Xue Rd.
Taichung, Taiwan, R.O.C.
- (3) Chung Chien Wang of 7F, No. 35, Yongfu Rd.
Shanhua Township, Tainan County 741, Taiwan, R.O.C.
- (4) Tzu-Hsuan Hsu of No. 72, Gangshan Central St.
Cianjhen District, Kaohsiung City 806, Taiwan, R.O.C.
- (5) Ching-Chun Wang of 3F-1, No. 28, Lane 158, Sec. 2, Dongmen Rd.
Tainan, Taiwan, R.O.C.

have invented certain improvements in

**A METHOD TO AVOID LASER ANNEAL BOUNDARY EFFECT
WITHIN (BSI) CMOS IMAGE SENSOR ARRAY**

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
x _____ filed on April 22, 2010 and
assigned application no. 12/765,496 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America,

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whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Kai-Chun Hsu

Residence Address: 3F, No. 116, Yongli Rd.
Yonghe City, Taipei County 234, Taiwan, R.O.C.

Dated: 2010/08/17

Kai-Chun Hsu
Inventor Signature

Inventor Name: Yeur-Luen Tu

Residence Address: No. 3-6, Lane 12, Gong-Xue Rd.
Taichung, Taiwan, R.O.C.

Dated: 2010/08/17

[Signature]
Inventor Signature

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Inventor Name: Chung Chien Wang

Residence Address: 7F, No. 35, Yongfu Rd.
Shanhua Township, Tainan County 741, Taiwan, R.O.C.

Dated: 2010.08.26

Chung Chien, Wang
Inventor Signature

Inventor Name: Tzu-Hsuan Hsu

Residence Address: No. 72, Gangshan Central St.
Cianjhen District, Kaohsiung City 806, Taiwan, R.O.C.

Dated: 2010.08.19

Tzu-Hsuan Hsu
Inventor Signature

Inventor Name: Ching-Chun Wang

Residence Address: 3F-1, No. 28, Lane 158, Sec. 2, Dongmen Rd.
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Dated: 2010.08.23

Ching-Chun Wang
Inventor Signature